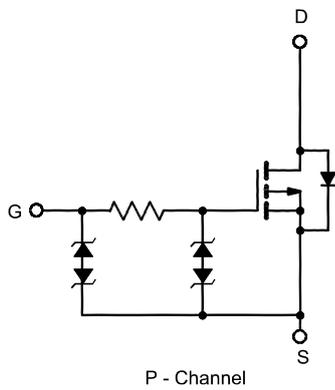


### GENERAL DESCRIPTION

The PT GEFÖÜ is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance.

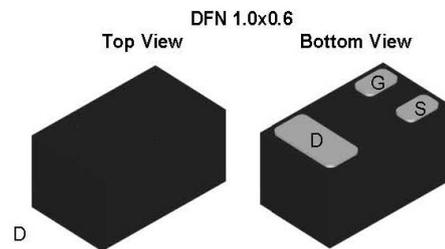
### APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System



### FEATURES

- $R_{DS(ON)} = 0.48\Omega @ V_{GS} = -4.5V$
- $R_{DS(ON)} = 0.67\Omega @ V_{GS} = -2.5V$
- $R_{DS(ON)} = 0.95\Omega @ V_{GS} = -1.8V$
- $R_{DS(ON)} = 2.20\Omega @ V_{GS} = -1.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- Capable doing Cu wire bonding



### Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)

| Parameter            | Symbol          | Maximum Ratings | Unit |
|----------------------|-----------------|-----------------|------|
| Drain-Source Voltage | V <sub>DS</sub> | -20             | V    |
| Gate-Source Voltage  | V <sub>GS</sub> | ±6              | V    |

Electrical Characteristics (T<sub>J</sub> = 25°C Unless Otherwise Specified)

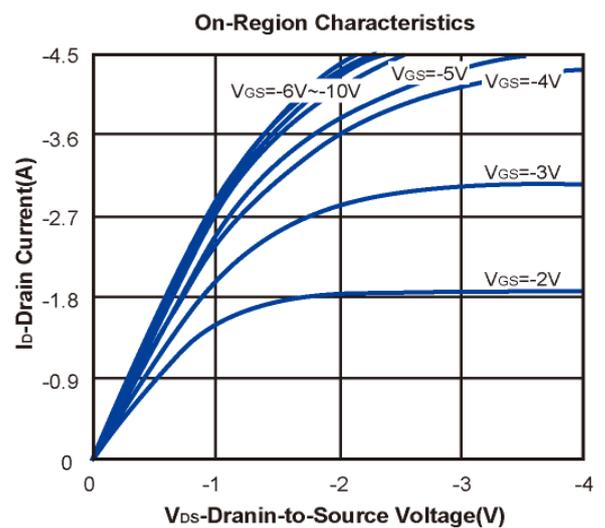
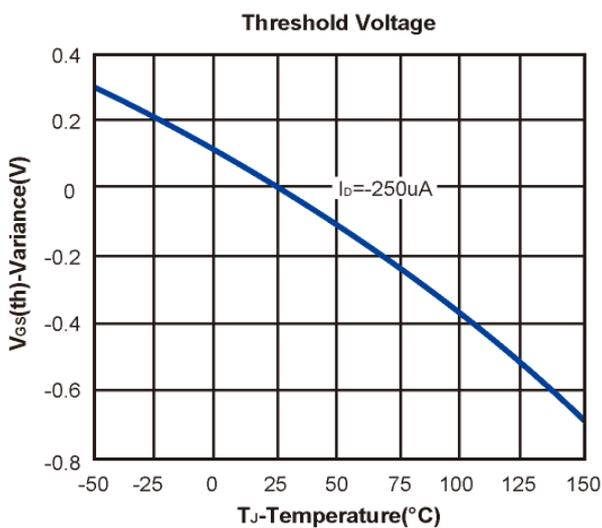
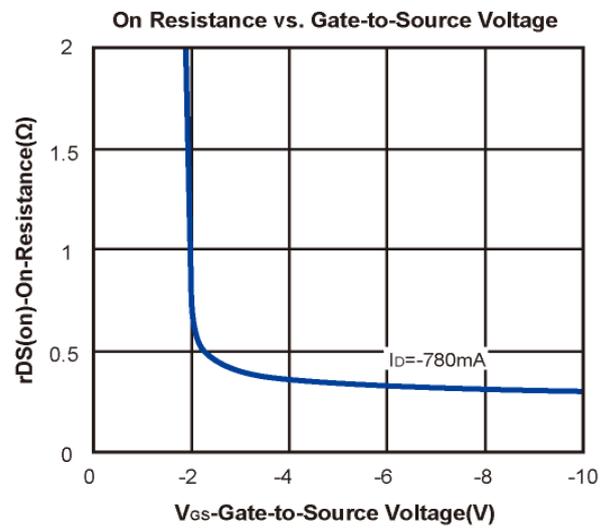
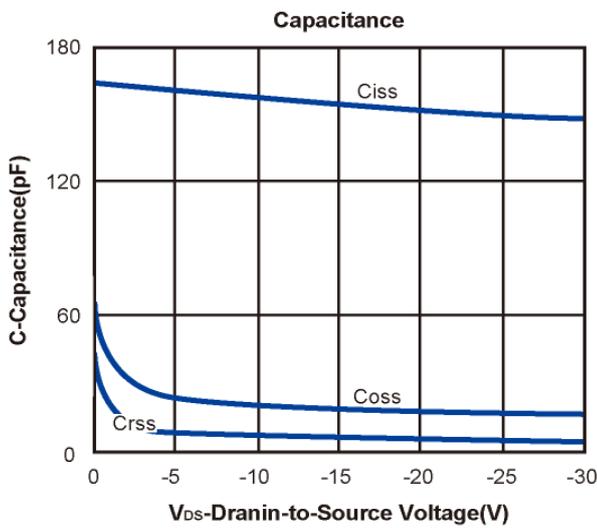
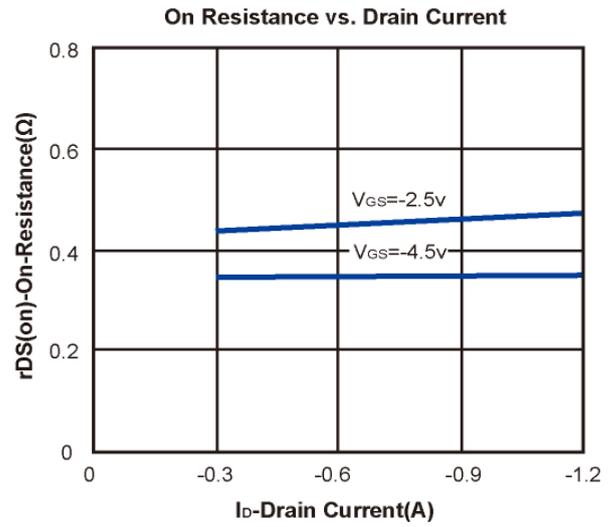
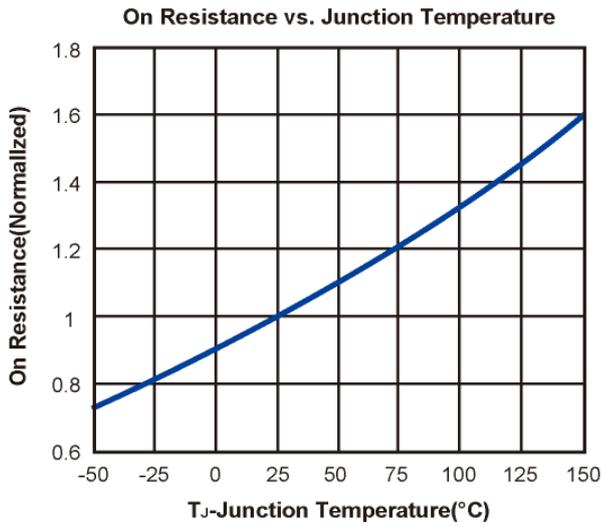
| Symbol              | Parameter                               | Limit  | Min   | Typ  | Max  | Unit |
|---------------------|---|--|-------|------|------|------|
| <b>STATIC</b>       |   |  |       |      |      |      |
| BV <sub>DSS</sub>   | Drain-Source Breakdown Voltage          | V <sub>GS</sub> =0V, I <sub>D</sub> =-250 μA   | -20   |      |      | V    |
| V <sub>GS(th)</sub> | Gate Threshold Voltage                  | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250 μA   | -0.45 |      | -1.2 | V    |
| I <sub>GSS</sub>    | Gate Leakage Current                    | V <sub>DS</sub> =0V, V <sub>GS</sub> =±4.5V  |       |      | ±10  | μA   |
| I <sub>DSS</sub>    | Zero Gate Voltage Drain Current         | V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V   |       |      | -1   | μA   |
| R <sub>DS(ON)</sub> | Drain-Source On-Resistance <sup>a</sup> | V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-780mA   |       | 0.35 | 0.48 | Ω    |
|                     |   | V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-660mA   |       | 0.44 | 0.67 |      |
|                     |   | V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-100mA   |       | 0.55 | 0.95 |      |
|                     |   | V <sub>GS</sub> =-1.5V, I <sub>D</sub> =-100mA   |       | 0.78 | 2.20 |      |
| V <sub>SD</sub>     | Diode Forward Voltage                   | I <sub>S</sub> =-350mA, V <sub>GS</sub> =0V  |       | -0.8 | -1.2 | V    |
| <b>DYNAMIC</b>      |   |  |       |      |      |      |
| C <sub>iss</sub>    | Input Capacitance                       | V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V, f=1MHZ   |       | 152  |      | pF   |
| C <sub>oss</sub>    | Output Capacitance                      |  |       | 18.5 |      |      |
| C <sub>rss</sub>    | Reverse Transfer Capacitance            |  |       | 6    |      |      |
| Q <sub>g</sub>      | Total Gate Charge                       | V <sub>DS</sub> =-16V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-200mA  |       | 2.8  |      | nC   |
| Q <sub>gs</sub>     | Gate-Source Charge                      |  |       | 2.1  |      |      |
| Q <sub>gd</sub>     | Gate-Drain Charge                       |  |       | 0.5  |      |      |
| t <sub>d(on)</sub>  | Turn-On Delay Time                      | V <sub>DD</sub> =-10V, R <sub>L</sub> =50Ω<br>V <sub>GEN</sub> =-5V, R <sub>G</sub> =10Ω<br>I <sub>D</sub> =-200mA |       | 51.3 |      | ns   |
| t <sub>r</sub>      | Turn-On Rise Time                       |  |       | 24.2 |      |      |
| t <sub>d(off)</sub> | Turn-Off Delay Time                     |  |       | 246  |      |      |
| t <sub>f</sub>      | Turn-Off Fall Time                      |  |       | 81.2 |      |      |

Notes: a. Based on Eutectic paste and bond wire Cu wire 1mil×1(S), Cu wire 1mil×1(G) on each die of SOT-523 package.

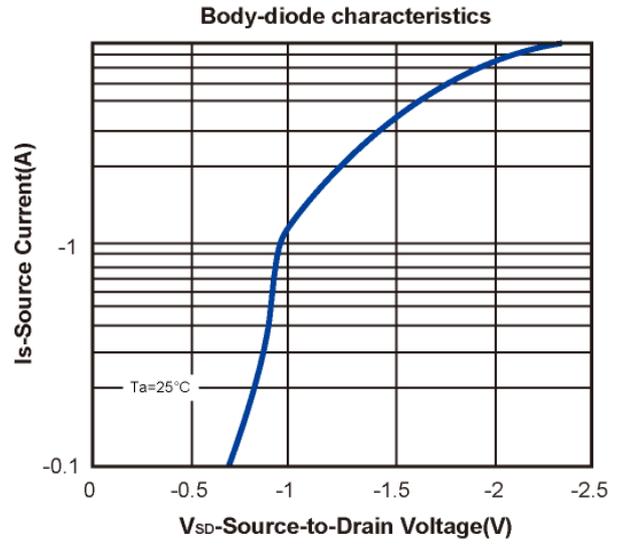
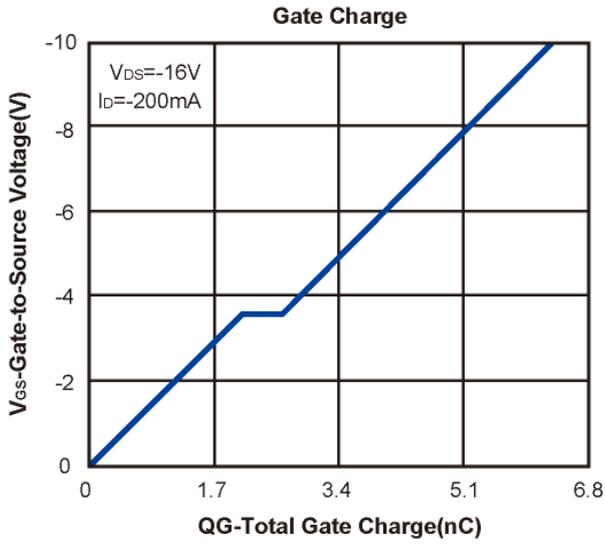
b. Pulse test; pulse width ≤ 300us, duty cycle ≤ 2%.

c. H&M SEMI reserves the right to improve product design, functions and reliability without notice.

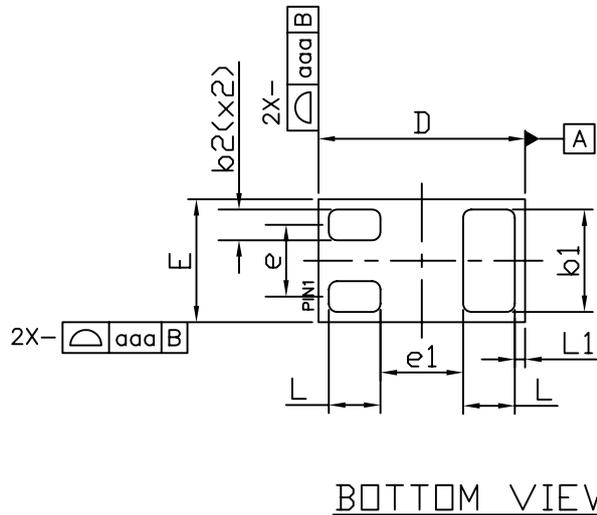
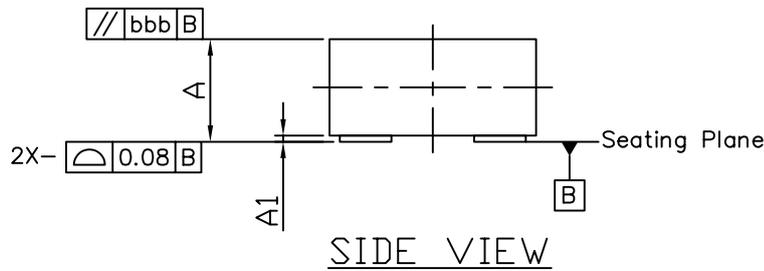
Typical Characteristics (T<sub>J</sub> =25°C Noted)



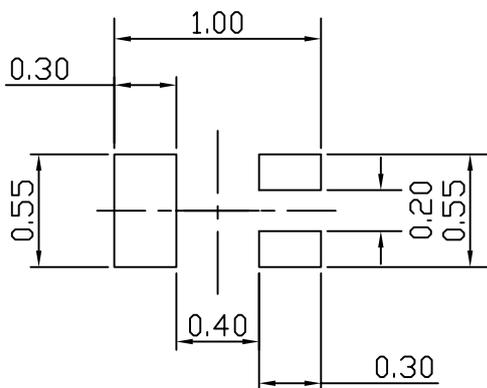
Typical Characteristics (T<sub>J</sub> =25°C Noted)



DFN1.0X0.6-3L



RECOMMENDED LAND PATTERN



| SYMBOLS | DIMENSIONS IN MILLIMETERS |      |       | DIMENSIONS IN INCHES |       |       |
|---------|---------------------------|------|-------|----------------------|-------|-------|
|         | MIN                       | NOM  | MAX   | MIN                  | NOM   | MAX   |
| A       | 0.50                      | 0.52 | 0.55  | 0.019                | 0.020 | 0.022 |
| A1      | 0.00                      | 0.03 | 0.05  | 0.000                | 0.001 | 0.002 |
| b1      | 0.45                      | 0.50 | 0.55  | 0.018                | 0.020 | 0.022 |
| b2      | 0.10                      | 0.15 | 0.20  | 0.004                | 0.006 | 0.008 |
| D       | 0.95                      | 1.00 | 1.075 | 0.037                | 0.039 | 0.042 |
| E       | 0.55                      | 0.60 | 0.675 | 0.022                | 0.024 | 0.027 |
| e       | ---                       | 0.35 | ---   | ---                  | 0.014 | ---   |
| e1      | ---                       | 0.40 | ---   | ---                  | 0.016 | ---   |
| L       | 0.20                      | 0.25 | 0.30  | 0.008                | 0.010 | 0.012 |
| L1      | ---                       | 0.05 | ---   | ---                  | 0.002 | ---   |
| aaa     | 0.15                      |      |       | 0.006                |       |       |
| bbb     | 0.05                      |      |       | 0.002                |       |       |

NOTE

1. ALL DIMENSION ARE IN MILLIMETERS. ANGLES ARE IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED HEAT SINK SLUG AS WELL AS THE TERMINALS.